

INTERNATIONAL STANDARD



**Printed electronics –
Part 301-1: Equipment – Contact printing – Rigid master – Measurement method
of plate master external dimension**



THIS PUBLICATION IS COPYRIGHT PROTECTED

Copyright © 2017 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigenda or an amendment might have been published.

IEC Catalogue - webstore.iec.ch/catalogue

The stand-alone application for consulting the entire bibliographical information on IEC International Standards, Technical Specifications, Technical Reports and other documents. Available for PC, Mac OS, Android Tablets and iPad.

IEC publications search - www.iec.ch/searchpub

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee,...). It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and also once a month by email.

Electropedia - www.electropedia.org

The world's leading online dictionary of electronic and electrical terms containing 20 000 terms and definitions in English and French, with equivalent terms in 16 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

IEC Glossary - www.iec.ch/glossary

65 000 electrotechnical terminology entries in English and French extracted from the Terms and Definitions clause of IEC publications issued since 2002. Some entries have been collected from earlier publications of IEC TC 37, 77, 86 and CISPR.

IEC Customer Service Centre - webstore.iec.ch/csc

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: csc@iec.ch.

INTERNATIONAL STANDARD



**Printed electronics –
Part 301-1: Equipment – Contact printing – Rigid master – Measurement method
of plate master external dimension**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 19.080; 37.100.10

ISBN 978-2-8322-4302-2

Warning! Make sure that you obtained this publication from an authorized distributor.

CONTENTS

FOREWORD.....	4
INTRODUCTION.....	6
1 Scope.....	7
2 Normative references	7
3 Terms and definitions	7
4 Measurement methods for geometrical size of plate master.....	11
4.1 General.....	11
4.2 Procedure A.....	11
4.2.1 Measuring instrument	11
4.2.2 Measurement of edge length	11
4.2.3 Edge squareness [1][2].....	12
4.2.4 Measurement of edge straightness	13
4.2.5 Thickness	14
4.3 Procedure B.....	15
4.3.1 Measuring instrument	15
4.3.2 Procedure.....	15
4.3.3 Report	16
5 Measurement method for flatness of plate master substrate [1].....	16
5.1 Measuring instrument.....	16
5.1.1 Method	16
5.1.2 Mechanical stylus measuring instrument.....	16
5.1.3 Optical stylus measuring instrument.....	16
5.1.4 Calibration.....	16
5.1.5 Environment control.....	17
5.1.6 Measurement conditions.....	17
5.1.7 Measurement location.....	17
5.2 Procedure	17
5.3 Report.....	18
6 Measurement method for surface roughness of plate master substrate [5].....	19
6.1 Measuring instrument.....	19
6.1.1 Method	19
6.1.2 Mechanical stylus measuring instrument.....	19
6.1.3 Optical stylus measuring instrument	19
6.1.4 Calibration.....	19
6.1.5 Environment control.....	19
6.1.6 Measurement conditions.....	19
6.1.7 Measurement location.....	19
6.2 Procedure	20
6.3 Report.....	20
Bibliography.....	21
Figure 1 – Illustration of the terms defined for measuring the geometrical size of a plate master.....	8
Figure 2 – Graphical illustration of flatness [1]	9
Figure 3 – Measurement procedure of edge length	12
Figure 4 – Measurement procedure of edge squareness	13

Figure 5 – Measurement procedure of edge straightness 14

Figure 6 – Measurement locations for geometrical size of plate using CMM 16

Table 1 – Example of profile measurement results 18

Table 2 – Example of flatness measurement results..... 18

Table 3 – Example of surface roughness measurement results 20

Currently in preview, click buy full version

INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED ELECTRONICS –

**Part 301-1: Equipment – Contact printing – Rigid master –
Measurement method of plate master external dimension**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, accept IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 62903-1 has been prepared by IEC technical committee:119: Printed electronics.

The text of this standard is based on the following documents:

FDIS	Report on voting
119/152/FDIS	119/162/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62899 series, published under the general title *Printed electronics*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

When dissecting the term “printed electronics”, it can be easily understood that this industry involves electronic devices and products that are made using some kind of printing technique. Printing methods have been widely used in textile and paper type substrates for centuries. In the past, the advent of mass producible printouts has brought huge impacts on how knowledge is stored, transferred and reproduced. At this current stage of technological development, printing on either rigid or flexible substrates is considered to supplement or replace traditional electronic device manufacturing processes. The difference between media printing and printed electronics stems from the fact that media print is used to convey information for humans to process using their eyes while printed electronics requires machines to process electronic information; the level of required resolution and functionality makes the difference. Some of the widely used functional materials for printed electronics are though not limited to: nano- or micro-size metal particles, semiconductive polymers, and dielectric materials. Due to the available and required readout resolution, small feature sizes below 20 μm need to be printed. Layer thickness and registration accuracy of printed products are closely related to the quality control of electronic devices and ink materials require a high level of quality. Overall, printing tolerance is much smaller in printed electronics.

There are two main categories in the printing process for the printed electronics. One is a non-contact printing process, such as inkjet printing and electrostatic discharge (ESD) printing process. The other is a contact printing process such as gravure printing, gravure offset printing, reverse offset printing and screen printing. This document provides a proposal for measuring and assessing the printing master, therefore the scope is limited to the printing process using the printing master.

The quality of the printing master is important because the ink is transferred from the printing master to the substrate directly in these processes, which means that the quality of the results of the printed circuit depends on the quality of the printing master. For a mass production of the printed electronic devices, many companies such as device manufacturers, printing master manufacturers and printing master manufacturing equipment vendors are related to manufacturing and they would be using the printing master and the standardized measurement and assessment methods.

PRINTED ELECTRONICS –

Part 301-1: Equipment – Contact printing – Rigid master – Measurement method of plate master external dimension

1 Scope

This part of IEC 62899 defines measurement terms and methods related to the external dimension of a rigid plate master.

Measurement terms include geometrical size such as edge length, edge squareness, edge straightness and thickness, flatness of plate master substrates, and surface roughness of plate master.

2 Normative references

There are no normative references in this document.

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1

plate master

device that carries the image to be printed

Note 1 to entry: The image on the plate may be raised above the surface (relief) or may be carved into the surface.

3.2

geometrical definition of plate master

definition which is needed in order to determine the shape and size of the plate

3.3

orientation corner

asymmetric corner specified for the purpose of mechanical orientation and the operator's visual confirmation of plate orientation

Note 1 to entry: This term is introduced graphically in Figure 1.